

AMENDMENTS TO THE SPECIFICATION

Please substitute the following paragraph for the paragraph beginning on page 1, line 9:

A transition from a waveguide to a microstrip is known from U.S. Patent No. 5,202,648.

Wherein, a microstrip is extended on an upper side of a substrate and an associated ground line, consisting of a conductive surface on an opposite side of the substrate, contacts the waveguide wall. A problem is that a waveguide and a contact strip designed in this way has a reflection attenuation that is frequently too low and a transmission attenuation which is too high.

Please substitute the following paragraph for the paragraph beginning on page 1, line 17:

A ground line associated with a microstrip includes a plurality of ground surfaces superimposed on one another, all of which contact one another by way of through-contacts in a substrate. The multi-layer ground line produces a more favorable field conversion from the microstrip to the waveguide, thereby a high reflection attenuation and a low transmission attenuation results.

Please substitute the following lines beginning on page 2, line 20:

Fig. 2 is a longitudinal section A-A through the transition of Fig. 1; and

Fig. 3 is a cross-section B-B through the transition of Fig. 1.

Please substitute the following paragraph for the paragraph beginning on page 3, line 8:

Now, additionally referring to Figs. 2 and 3, there is shown two ground surfaces 7 and 8, in Fig. 2, which are applied to the upper side of substrate 1 next to microstrip 2. A plurality of ground surfaces 9, as illustrated in Fig. 3, are superimposed on one another within multi-layer substrate 1 each having the same ground potential. Cross-section B-B, through waveguide 3 into

substrate 1, shown in Fig. 3 shows multi-layer ground surfaces 9 within substrate 1.

Please substitute the following paragraph for the paragraph beginning on page 4, line 14:

Substrate 1 is fixed to support 14 (see Figs. 2 and 3) beneath opening 4 by at least one screw; there being two screws 12 and 13 in the embodiment shown in Fig. 2. Screws 12 and 13 lie with their heads on ground surfaces 7 and 8 next to microstrip 2 and screws 12 and 13 make an electrical contact between ground surfaces 7 and 8 and ground surfaces 9 superimposed on one another in substrate 1 and support 14. Support 14 additionally serves as a waveguide wall 14 as can be seen in Fig. 3. Since electrical contact is additionally made between ground lines 7 and 8, applied to the upper side of substrate 1, and waveguide wall 14, the transmission attenuation of the transition is reduced. This contact can, as shown in Fig. 2, be made by two conductive ribbons 15 and 16, which are clamped at one end between the heads of screws 12 and 13 and conductive surfaces 7 and 8. The other end of conductive ribbons 15 and 16 extend into a wall of waveguide 3 along and at their other end in parting plane 17 of waveguide 3. Waveguide 3 includes, including two half shells that are joined along parting plane 17.

AMENDMENTS TO THE DRAWINGS

Please amend Fig. 3 as indicated in red on the attached annotated marked-up drawing, by adding surface 7, 8 along with the identifier and the addition of identifier 1, which is directed to an upper side of substrate 1. A replacement sheet presenting replacement figures which incorporate the desired changes is also enclosed.